

Top Fabrication (Scale 1:3)

Stackup Table

Layer Name	Type	Material	Thickness (mm)	Color
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified
F.Paste	Top Solder Paste		0 mm	
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified
F.Cu	copper		0.035 mm	
Dielectric	prepreg	FR4	0.1 mm	Not specified
In1.Cu	copper		0.035 mm	
Dielectric	core	FR4	1.24 mm	Not specified
In2.Cu	copper		0.035 mm	
Dielectric	prepreg	FR4	0.1 mm	Not specified
B.Cu	copper		0.035 mm	
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified
B.Paste	Bottom Solder Paste		0 mm	
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified

FABRICATION NOTES (UNLESS OTHERWISE SPECIFIED)

- 1) OUTLINE DEFINED IN SEPARATE GERBER FILE WITH "Edge_Cuts.GBR" SUFFIX.
DIMENSIONS OF CIRCUMSIZED RECTANGLE SHOWN ON THIS DWG FOR REF ONLY.
- 2) SEE SEPARATE DRILL FILES WITH ".DRL" SUFFIX FOR HOLE LOCATIONS.SELECTED HOLE LOCATIONS SHOWN ON THIS DWG FOR REF ONLY.
- 3) IMPEDANCE CONTROL REQUIRED.
Microstrip 90-Ohm Differential (USB)
0.5334 mm width, 0.2032 mm spacing
- 4) CONFIRM TRACE WIDTHS AND SPACINGS.
- 5) DESIGN GEOMETRY MINIMUM FEATURE SIZES:

TRACE WIDTH0.16 mm

TRACE TO TRACE0.20 mm

MIN. HOLE (PTH)0.4 mm

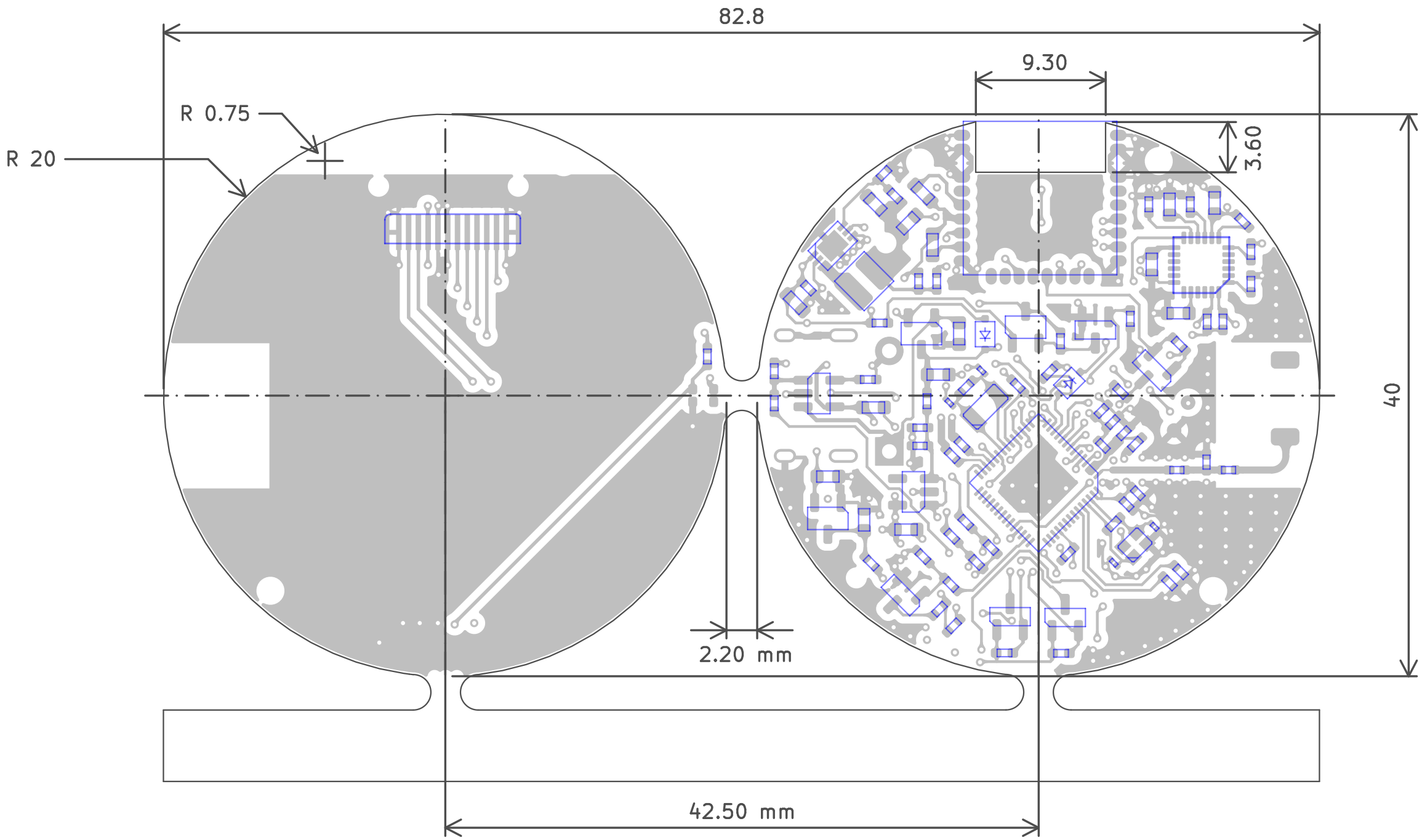
MIN. HOLE (NPTH)0.2 mm

ANNULAR RING0.1 mm

COPPER TO HOLE0.25 mm

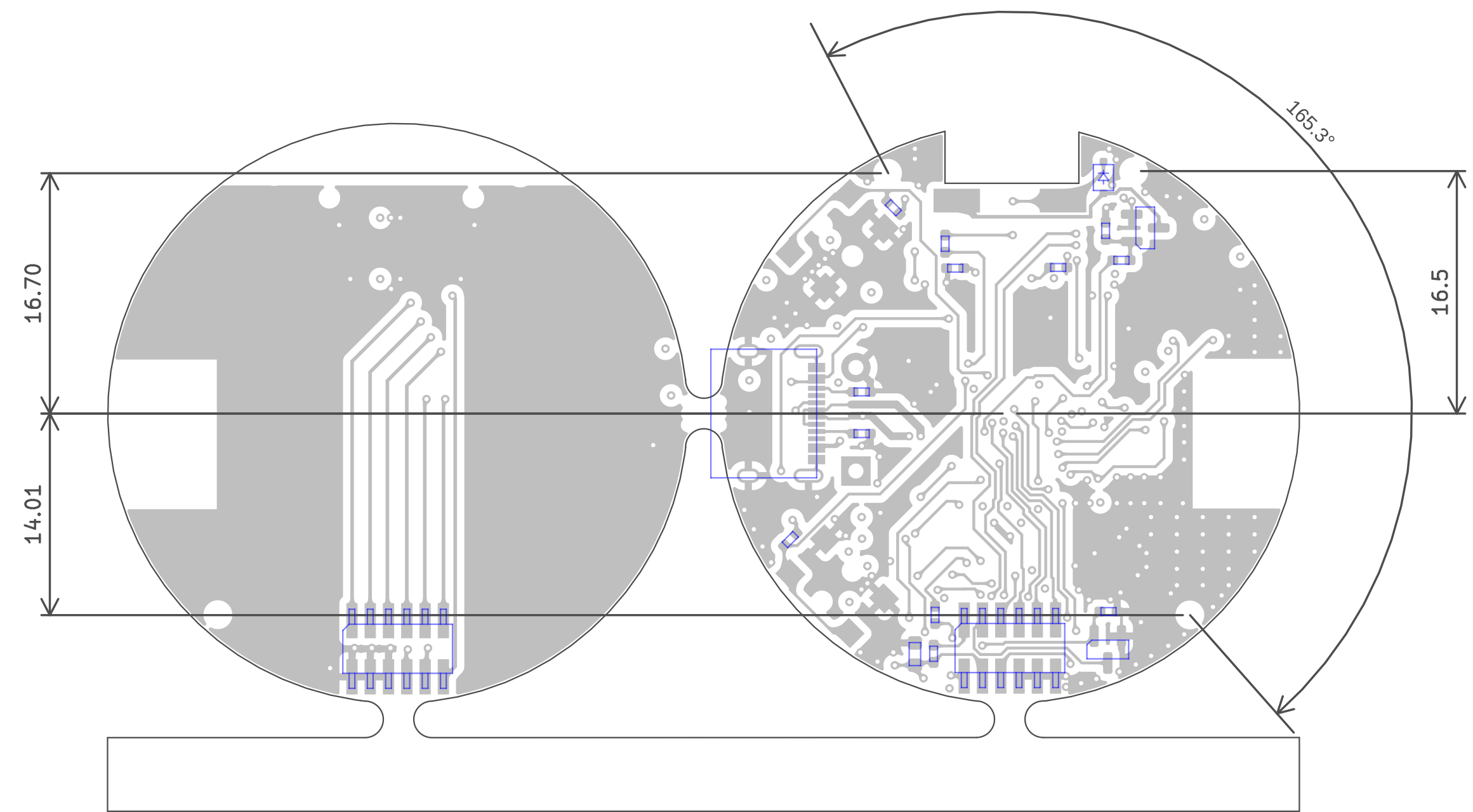
COPPER TO EDGE0.2 mm

HOLE TO HOLE0.3 mm



All dimensionsarein millimeters unless otherwise specified.

Bottom Fabrication (Scale 1:3)



All dimensions are in millimeters unless otherwise specified.